

GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
RAJYA SABHA
UNSTARRED QUESTION NO. 1343
TO BE ANSWERED ON: 02.08.2024

SEMICONDUCTOR CHIP FABRICATION

1343. SHRI KARTIKEYA SHARMA:

Will the Minister of Electronics and Information Technology be pleased to state:

- (a) the major Government and private companies engaged in semiconductor chip fabrication, their installed capacity and the fabrication capabilities in terms of transistor density;
- (b) the global standard for chip fabrication in terms of transistor density and the current indigenous capacity; and
- (c) the steps taken by Government in making the Indian chip fabrication industry gain access to cutting edge resources, funding and technology?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (c): Government has approved Semicon India programme with a total outlay of INR 76,000 crore for the development of semiconductor and display manufacturing ecosystem in the country. The programme aims to provide financial support to companies investing in semiconductors, display manufacturing and design ecosystem.

Following four schemes have been introduced under the aforesaid programme:

- a) **‘Modified Scheme for setting up of Semiconductor Fabs in India’** extends a fiscal support of 50% of the project cost on *pari-passu* basis for setting up of Silicon CMOS based Semiconductor Fabs in India.
- b) **‘Modified Scheme for setting up of Display Fabs in India’** extends fiscal support of 50% of Project Cost on *pari-passu* basis for setting up of Display Fabs in India.
- c) **‘Modified Scheme for setting up of Compound Semiconductors / Silicon Photonics / Sensors Fab / Discrete Semiconductors Fab and Semiconductor Assembly, Testing, Marking and Packaging (ATMP) / OSAT facilities in India’** extends a fiscal support of 50% of the Capital Expenditure on *pari-passu* basis for setting up of Compound Semiconductors / Silicon Photonics (SiPh) / Sensors (including MEMS) Fab/ Discrete Semiconductor Fab and Semiconductor ATMP / OSAT facilities in India.
- d) **‘Design Linked Incentive (DLI) Scheme’**: In addition to the design infrastructure support, the scheme provides “Product Design Linked Incentive” of up to 50% of the eligible expenditure subject to a ceiling of ₹15 Crore per application and “Deployment Linked Incentive” of 6% to 4% of net sales turnover over 5 years subject to a ceiling of ₹30 Crore per application.
- e) Government has also approved modernisation of Semi-Conductor Laboratory, Mohali as a brownfield Fab.

4 semiconductor units with cumulative investment of Rs 1,48,746 Cr have been approved under the Semicon India Programme.
